

## 1. General description

Ultrafast power diode in a SOD113A (2-lead TO-220F) plastic package.

## 2. Features and benefits

- Fast switching
- Very low on-state loss
- Low leakage current
- Low thermal resistance
- Isolated package

## 3. Applications

- Active PFC in air conditioner
- S.M.P.S Power Factor Correction (PFC)
- Half-bridge / full-bridge switched-mode power supplies

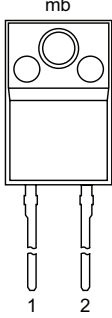
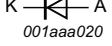
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
<b>Absolute maximum rating</b>						
$V_{RRM}$	repetitive peak reverse voltage		600			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_h \leq 45$ °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	30			A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25$ $\mu$ s; $T_h \leq 45$ °C; square-wave pulse	60			A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; <a href="#">Fig. 4</a>	290			A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse;	330			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 30$ A; $T_j = 25$ °C; <a href="#">Fig. 6</a>	-	1.18	1.55	V
		$I_F = 30$ A; $T_j = 150$ °C; <a href="#">Fig. 6</a>	-	0.98	-	V
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_F = 1$ A; $V_R = 30$ V; $di_F/dt = 50$ A/ $\mu$ s; $T_j = 25$ °C; <a href="#">Fig. 7</a>	-	42	75	ns
		$I_F = 30$ A; $V_R = 400$ V; $di_F/dt = 200$ A/ $\mu$ s; $T_j = 25$ °C; <a href="#">Fig. 7</a>	-	65	-	ns
		$I_F = 30$ A; $V_R = 400$ V; $di_F/dt = 200$ A/ $\mu$ s; $T_j = 125$ °C; <a href="#">Fig. 7</a>	-	101	-	ns

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	n.c.	mounting base; isolated		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BYV30X-600P	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 2-lead TO-220 "full pack"	SOD113A

## 7. Marking

Table 4. Marking codes

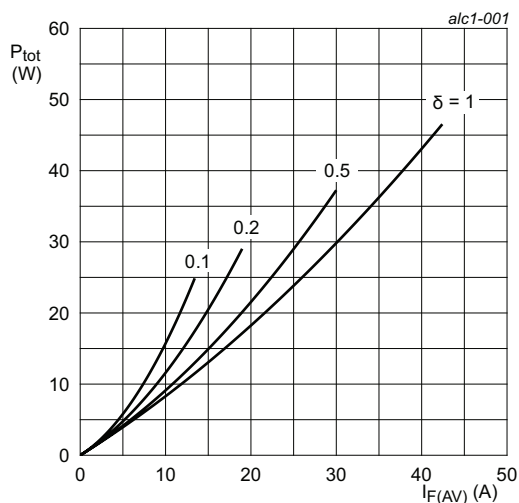
Type number	Marking codes
BYV30X-600P	BYV30X-600P

## 8. Limiting values

**Table 5. Limiting values**

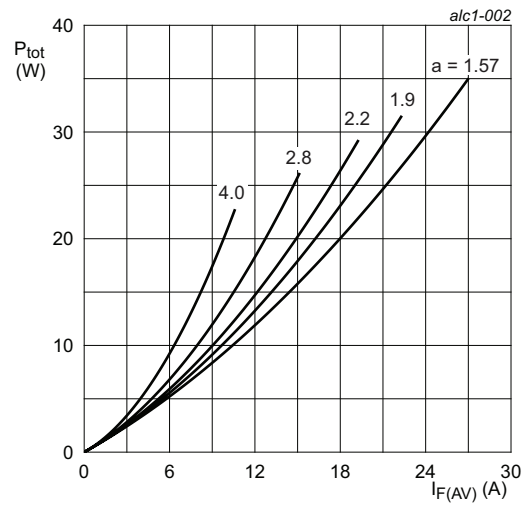
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		600	V
$V_{RWM}$	crest working reverse voltage		600	V
$V_R$	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_h \leq 45\text{ }^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	30	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_h \leq 45\text{ }^\circ\text{C}$ ; square-wave pulse	60	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>	290	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse;	330	A
$T_{stg}$	storage temperature		-55 to 175	$^\circ\text{C}$
$T_j$	junction temperature		175	$^\circ\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

**Fig. 1. Forward power dissipation as a function of average forward current; square waveform**



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

**Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform**

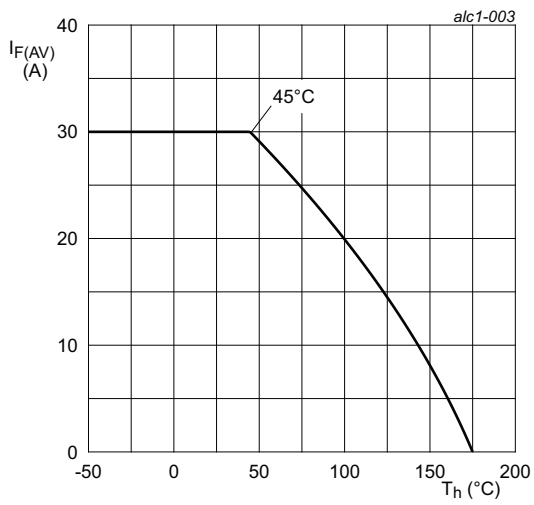


Fig. 3. Forward current as a function of heatsink temperature

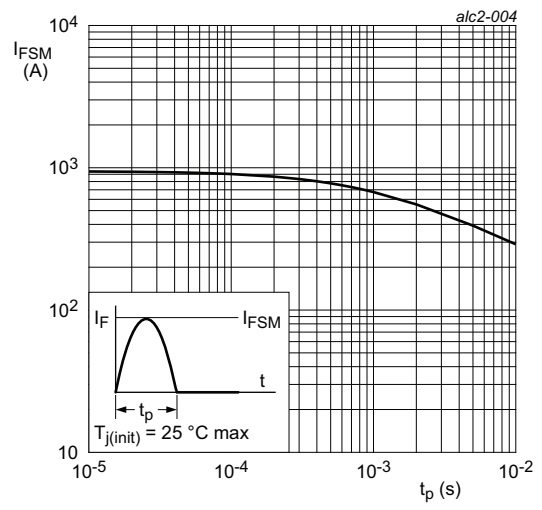


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>	-	-	3.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

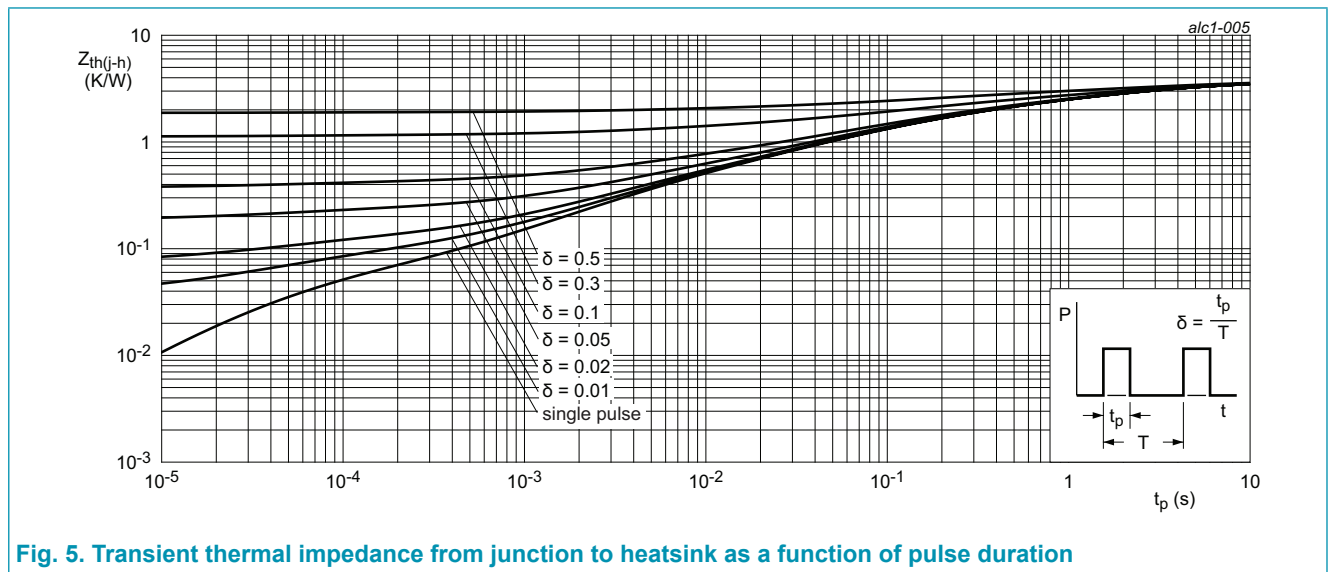
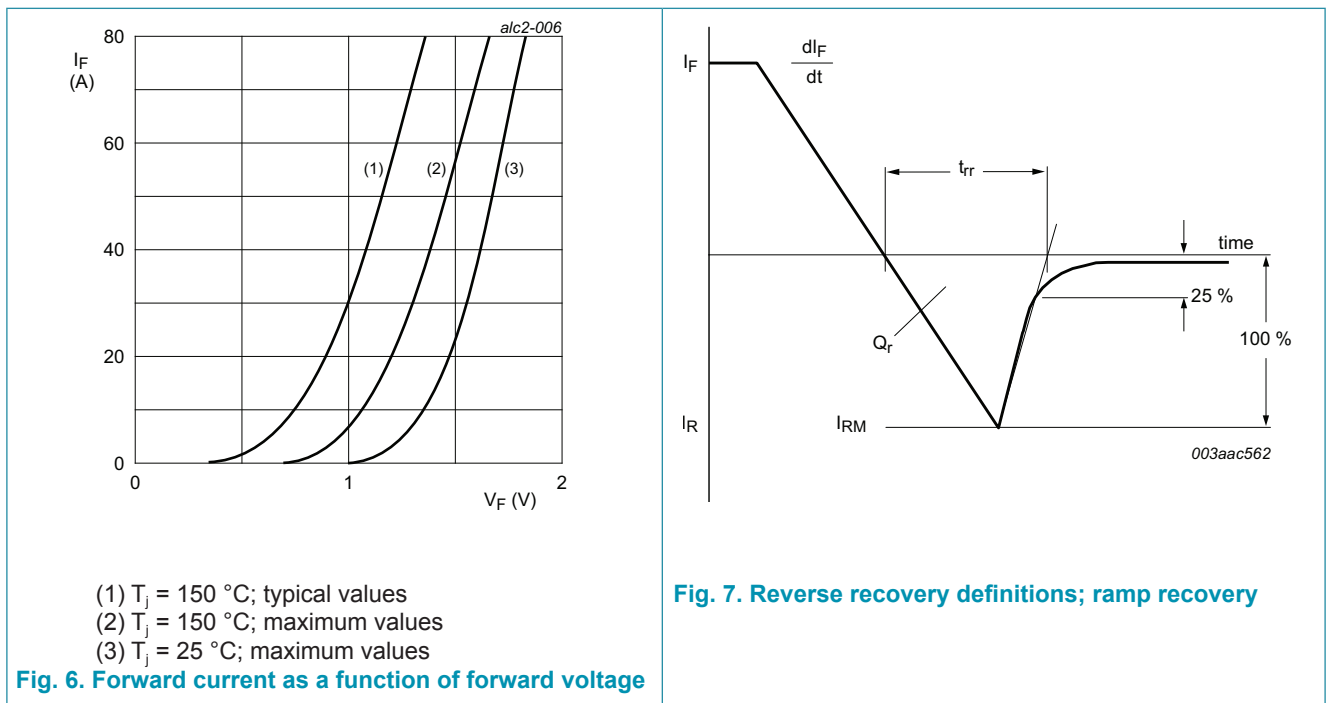


Fig. 5. Transient thermal impedance from junction to heatsink as a function of pulse duration

### 10. Characteristics

Table 7. Characteristics

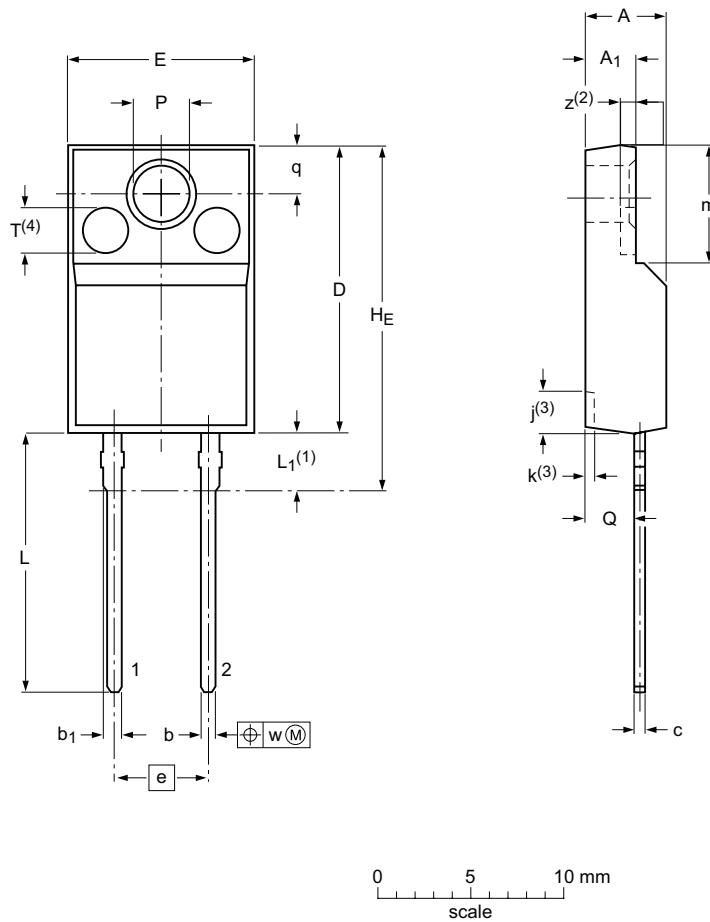
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward current	$I_F = 30\text{ A}; T_j = 25\text{ °C}; \text{Fig. 6}$	-	1.18	1.55	V
		$I_F = 30\text{ A}; T_j = 150\text{ °C}; \text{Fig. 6}$	-	0.98	-	V
$I_R$	reverse current	$V_R = 600\text{ V}; T_j = 25\text{ °C}$	-	2	10	$\mu\text{A}$
		$V_R = 600\text{ V}; T_j = 125\text{ °C}$	-	-	500	$\mu\text{A}$
<b>Dynamic characteristics</b>						
$Q_r$	reverse charge	$I_F = 30\text{ A}; V_R = 400\text{ V}; di_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$	-	272	-	nC
		$I_F = 30\text{ A}; V_R = 400\text{ V}; di_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C}; \text{Fig. 7}$	-	775	-	nC
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; di_F/dt = 50\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$	-	42	75	ns
		$I_F = 30\text{ A}; V_R = 400\text{ V}; di_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$	-	65	-	ns
		$I_F = 30\text{ A}; V_R = 400\text{ V}; di_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C}; \text{Fig. 7}$	-	101	-	ns
$I_{RM}$	peak reverse recovery current	$I_F = 30\text{ A}; V_R = 400\text{ V}; di_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$	-	8.4	-	A
		$I_F = 30\text{ A}; V_R = 400\text{ V}; di_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C}; \text{Fig. 7}$	-	15.2	-	A



### 11. Package outline

Plastic single-ended package; isolated heatsink mounted;  
1 mounting hole; 2-lead TO-220F 'full pack'

SOD113A



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	b <sub>1</sub>	c	D	E	e	H <sub>E</sub> max	j <sup>(3)</sup>	k <sup>(3)</sup>	L	L <sub>1</sub> <sup>(1)</sup>	m	P	Q	q	T <sup>(4)</sup>	W	z <sup>(2)</sup>	
mm	max	4.6	3.1	0.9	1.1	0.7	15.8	10.3		2.7	0.8	14.4	3.3	6.5	3.2	2.8		2.6	2.55	0.4	0.8
	nom							5.08	19.0												
	min	4.0	2.5	0.7	0.9	0.4	15.2	9.7		1.7	0.4	13.5	2.8	6.3	3.0	2.3					

Note

1. Terminals are uncontrolled within zone L1.
2. z is depth of T.
3. Dot lines area designs may vary.
4. Eject pin mark is for reference only.

sod113a\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOD113A	2 LEADS TO220F				<del>14-01-14</del> 14-04-10

Fig. 8. Package outline SOD113A

## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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## 13. Contents

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1. General description.....	1
2. Features and benefits .....	1
3. Applications .....	1
4. Quick reference data .....	1
5. Pinning information.....	2
6. Ordering information.....	2
7. Marking.....	2
8. Limiting values .....	3
9. Thermal characteristics .....	5
10. Characteristics.....	6
11. Package outline .....	7
12. Legal information .....	8
13. Contents .....	10

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